

## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	1 A
$V_{RRM}$	60 V
$T_j$ (max)	150°C
$V_F$ (max)	0.57 V

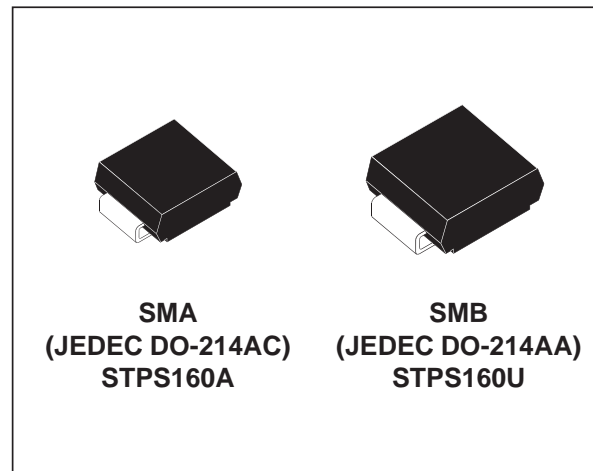
### FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- SURFACE MOUNTED DEVICE
- AVALANCHE CAPABILITY SPECIFIED

### DESCRIPTION

Single chip Schottky rectifier suited for Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in SMA or SMB, this device is intended for surface mounting and used in low voltage, high frequency inverters, free wheeling and polarity protection applications.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		60	V
$I_{F(RMS)}$	RMS forward current		10	A
$I_{F(AV)}$	Average forward current	$T_{Lead} = 130^{\circ}C \quad \delta = 0.5$	1	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms}$ Sinusoidal	75	A
$I_{RRM}$	Repetitive peak reverse current	$t_p = 2 \mu\text{s}$ square $F = 1\text{kHz}$	1	A
$I_{RSM}$	Non repetitive peak reverse current	$t_p = 100 \mu\text{s}$ square	1	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1 \mu\text{s} \quad T_j = 25^{\circ}C$	2400	W
$T_{stg}$	Storage temperature range		- 65 to + 150	°C
$T_j$	Maximum junction temperature *		150	
$dV/dt$	Critical rate of rise of reverse voltage		10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$  thermal runaway condition for a diode on its own heatsink

# STPS160A/U

## THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30	$^{\circ}\text{C}/\text{W}$
		SMB	23	

## STATIC ELECTRICAL CHARACTERISTICS

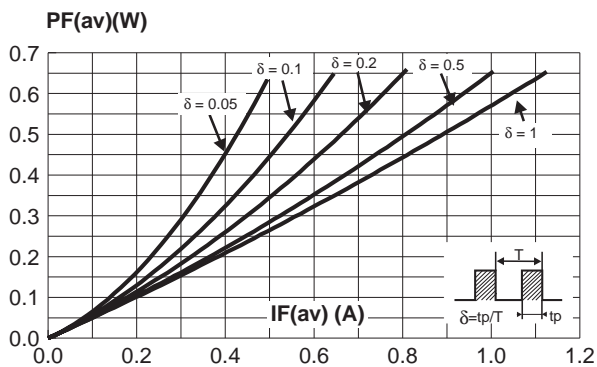
Symbol	Tests Conditions	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = 60\text{V}$			4	$\mu\text{A}$
		$T_j = 125^{\circ}\text{C}$			1.1	4	$\text{mA}$
$V_F^*$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 1\text{A}$			0.67	$\text{V}$
		$T_j = 125^{\circ}\text{C}$	$I_F = 1\text{A}$		0.49	0.57	
		$T_j = 25^{\circ}\text{C}$	$I_F = 2\text{A}$			0.8	
		$T_j = 125^{\circ}\text{C}$	$I_F = 2\text{A}$		0.58	0.65	

Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

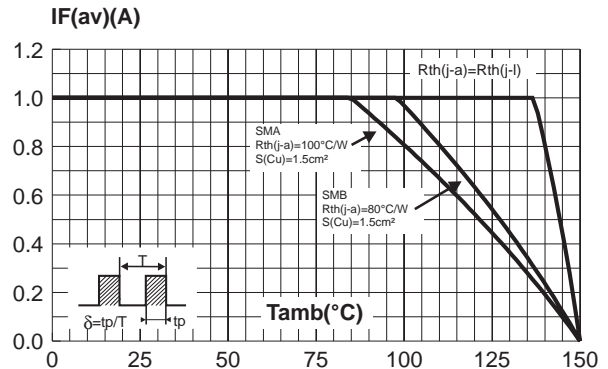
To evaluate the maximum conduction losses use the following equation :

$$P = 0.49 \times I_{F(AV)} + 0.08 \times I_{F(RMS)}^2$$

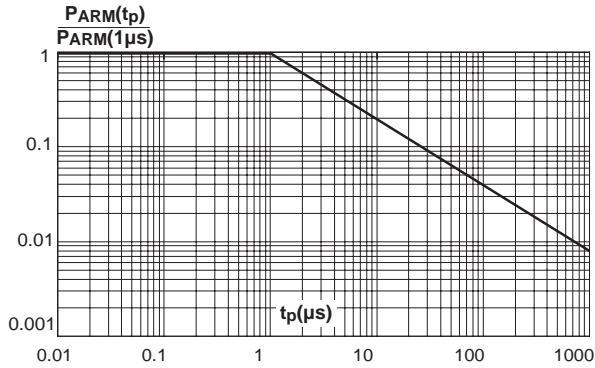
**Fig. 1:** Average forward power dissipation versus average forward current.



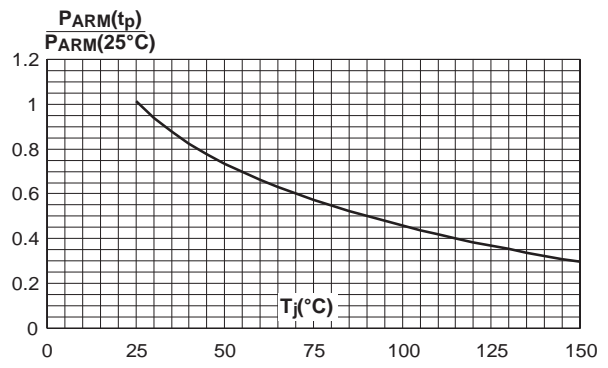
**Fig. 2:** Average forward current versus ambient temperature ( $\delta=0.5$ ).



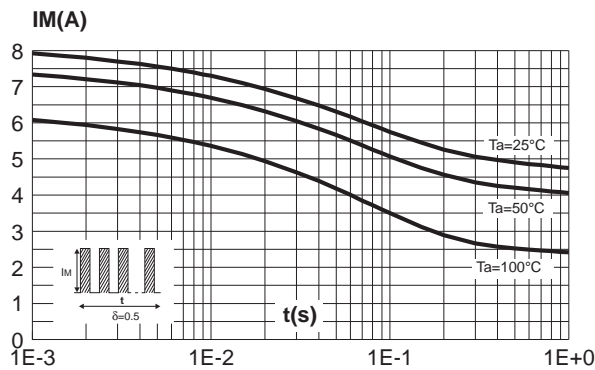
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



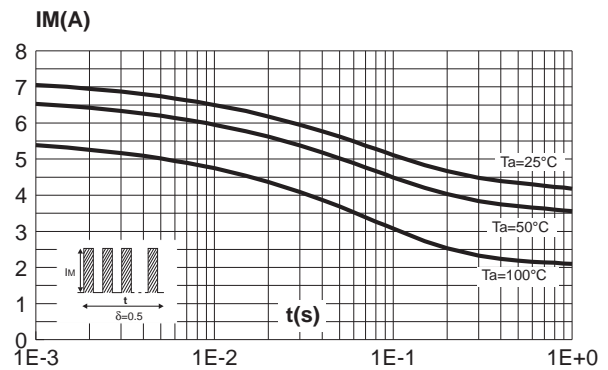
**Fig. 4:** Normalized avalanche power derating versus junction temperature.



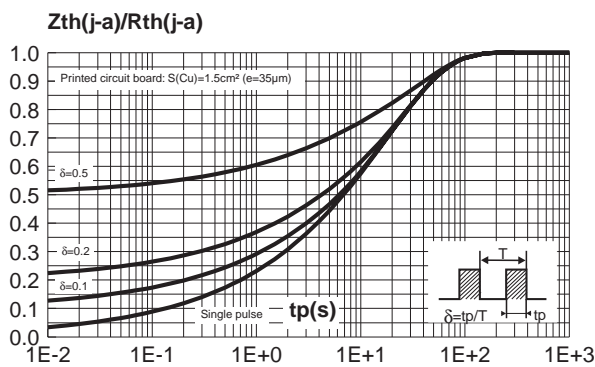
**Fig. 5-1:** Non repetitive surge peak forward current versus overload duration (maximum values) (SMB).



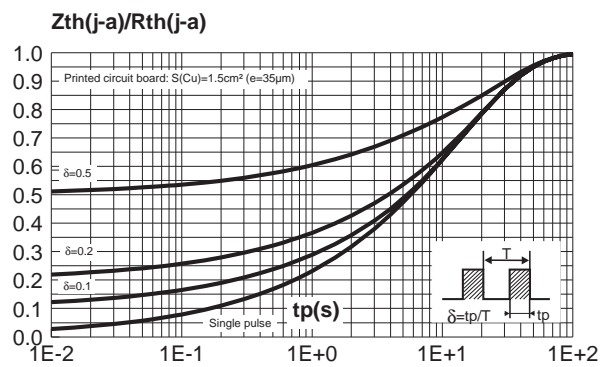
**Fig. 5-2:** Non repetitive surge peak forward current versus overload duration (maximum values) (SMA).



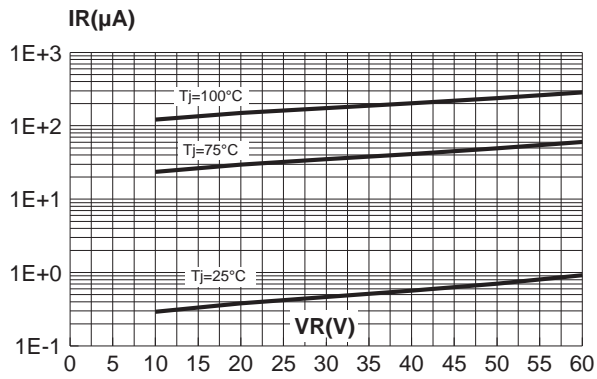
**Fig. 6-1:** Relative variation of thermal impedance junction to ambient versus pulse duration (SMB).



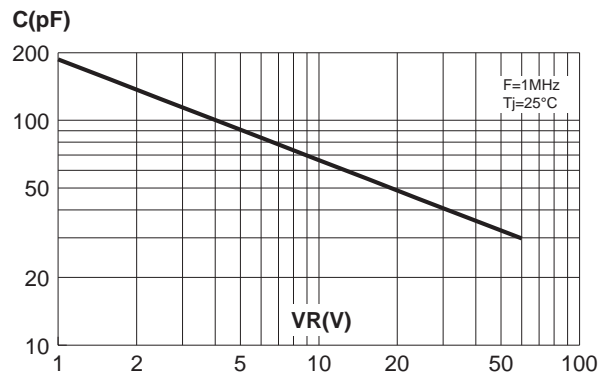
**Fig. 6-2:** Relative variation of thermal impedance junction to ambient versus pulse duration (SMA).



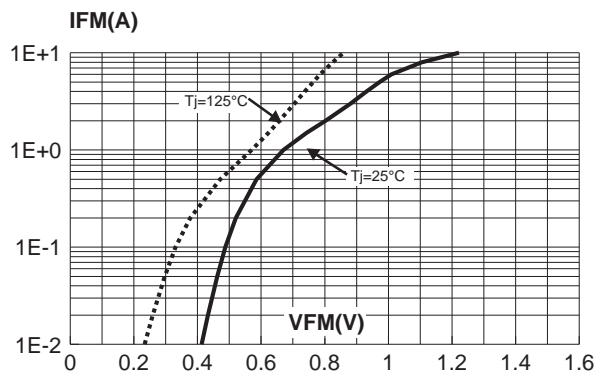
**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values).



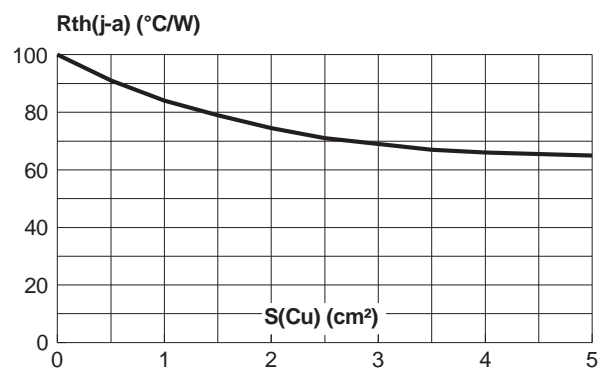
**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values).



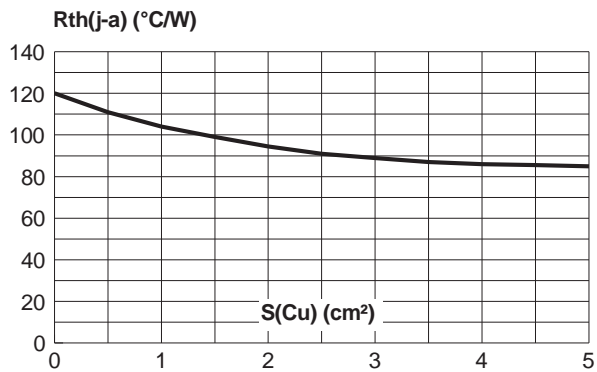
**Fig. 9:** Forward voltage drop versus forward current (maximum values).



**Fig. 10-1:** Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board, copper thickness: 35μm)(SMB).



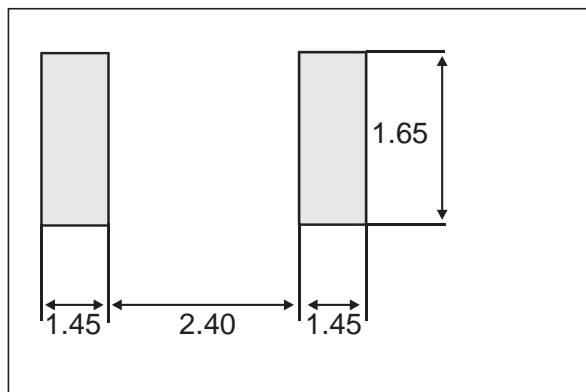
**Fig. 10-2:** Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board, copper thickness: 35μm)(SMA).



**PACKAGE MECHANICAL DATA**  
SMA

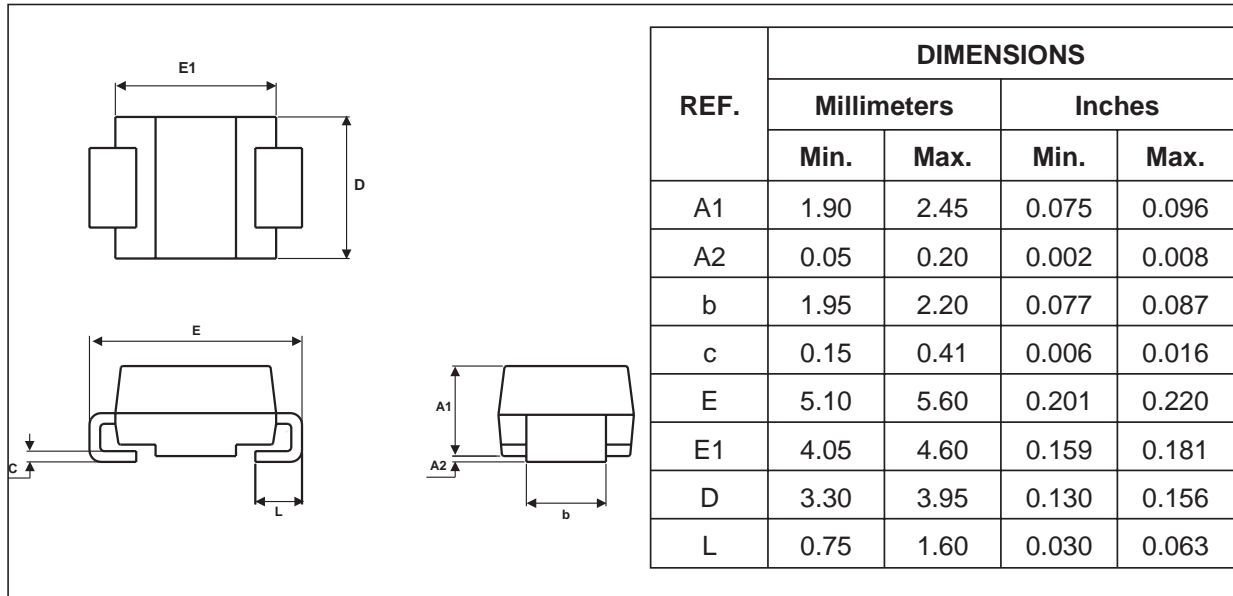
REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.70	0.075	0.106
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.41	0.006	0.016
E	4.80	5.60	0.189	0.220
E1	3.95	4.60	0.156	0.181
D	2.25	2.95	0.089	0.116
L	0.75	1.60	0.030	0.063

**FOOT PRINT DIMENSIONS ( in millimeters)**

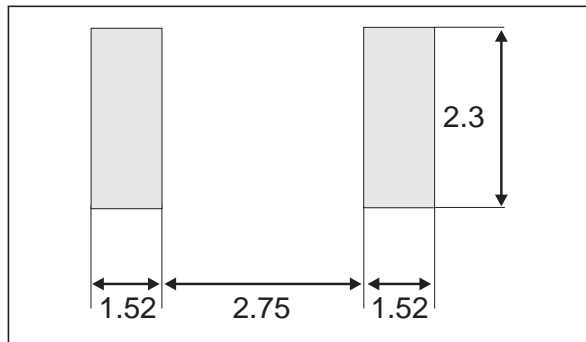


# STPS160A/U

## PACKAGE MECHANICAL DATA SMB



### FOOT PRINT DIMENSIONS ( in millimeters)



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS160A	GA6	SMA	0.068 g.	5000	Tape & reel
STPS160U	E16	SMB	0.107 g.	2500	Tape & reel

- BAND INDICATES CATHODE
- EPOXY MEETS UL94,V0

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